

EAST Search History**EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S23	80	Ohuchi-Shinji.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 14:00
S25	30	Yamada-shigeru.in. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:13
S26	36	Shiraishi-Yasushi.in. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:15
S27	339	257/685.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:15
S28	1388	257/686.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:16
S29	266	S28 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:17
S30	873	257/723.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:18
S31	260	S30 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:19
S32	1068	257/777.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:19

S33	196	S32 and (@ad<= "19991215" @pd<= "19991215" @rlad<= "19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:19
S34	1567	257/778.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:19
S35	540	S34 and (@ad<= "19991215" @pd<= "19991215" @rlad<= "19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:19
S36	302	257/782.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:20
S37	448	257/783.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:20
S38	829	257/784.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:20
S39	256	S38 and (@ad<= "19991215" @pd<= "19991215" @rlad<= "19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:20
S40	348	257/773.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:21
S41	1272	257/787.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:22
S42	516	S41 and (@ad<= "19991215" @pd<= "19991215" @rlad<= "19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:22

S43	257	257/673.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:22
S44	559	257/786.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:22
S45	156	257/790.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:23
S46	1223	257/737.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:23
S47	363	S46 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:24
S48	1186	257/738.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:24
S49	398	S48 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:24
S50	64	257/E25.006 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:24
S51	111	257/E25.013 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:25
S52	25	257/E25.018 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:25

S53	30	257/E25.021 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:25
S54	46	257/E25.027 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:25
S55	29	257/E21.614 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:25
S56	104	257/E23.085 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:26
S57	20	257/E31.117 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:26
S58	6	257/E31.118 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:26
S59	5	257/E51.02 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:26
S60	82	257/E23.116 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/31 15:27

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